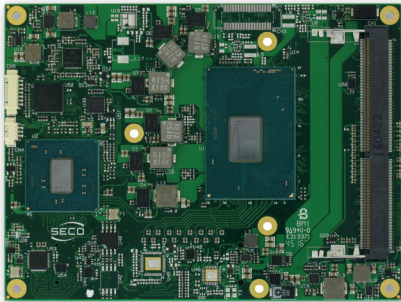




## COMe-B09-BT6

COM Express® Basic Type 6 with Intel® 6th and 7th generation Core™ / Xeon® (formerly Skylake and Kaby Lake) CPUs

When high graphics and Hyper-threading matter

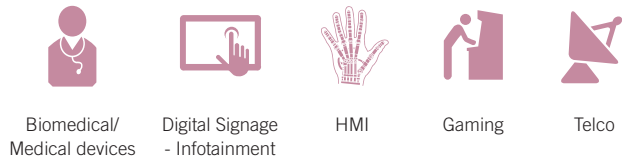


### HIGHLIGHTS

<b>CPU</b> Intel® 6th and 7th generation Core™ / Xeon® CPUs	<b>CONNECTIVITY</b> 4x USB 3.0; 8x USB 2.0; 8x PCI-e x1 Gen3; PEG x16 Gen3
<b>GRAPHICS</b> Intel® HD Graphics 530 /P530/630/P630	<b>MEMORY</b> 2 x DDR4 So-DIMM slots



### MAIN FIELDS OF APPLICATION



### FEATURES

<b>Processor</b>	Intel® Core™ <b>i3-6102E</b> , Dual Core @ 1.9GHz, 3MB Cache, 25W TDP Intel® Core™ <b>i3-6100E</b> , Dual Core @ 2.7GHz, 3MB Cache, 35W TDP Intel® Core™ <b>i5-6442EQ</b> , Quad Core @ 1.9GHz (2.7GHz in Turbo Boost), 6MB Cache, 25W TDP Intel® Core™ <b>i5-6440EQ</b> , Quad Core @ 2.7GHz (3.4GHz in Turbo Boost), 6MB Cache, 25W TDP Intel® Core™ <b>i7-6822EQ</b> , Quad Core @ 2GHz (2.8GHz in Turbo Boost), 8MB Cache, 25W TDP Intel® Core™ <b>i7-6820EQ</b> , Quad Core @ 2.8GHz (3.5GHz in Turbo Boost), 8MB Cache, 45W TDP Intel® Xeon® <b>E3-1505M V5</b> , Quad Core @ 2.8GHz (3.7GHz in Turbo Boost), 8MB Cache, 45W TDP Intel® Xeon® <b>E3-1515M V5</b> , Quad Core @ 2.8 GHz, 8MB Cache, 45W TDP (ECC supported), GT4E LINE (DO) with OPC (AO)
<b>Max Cores</b>	4
<b>Max Thread</b>	8 (HT not available with 6th Generation Core™ i5 and 7th Generation Core™ i3/i5 Processors)
<b>Chipset</b>	Skylake Platform: Intel® QM170, HM170 or CM236 PCH KabyLake Platform: Intel® QM175 or CM238 PCH
<b>Memory</b>	Up to two DDR4 SO-DIMM Slots supporting DDR4-2133 (DDR4-2400 for 7th Generation processors) Memory ECC DDR4 memory modules supported only with Xeon® and Core™ i3 processors combined with CM236 / CM238 PCH

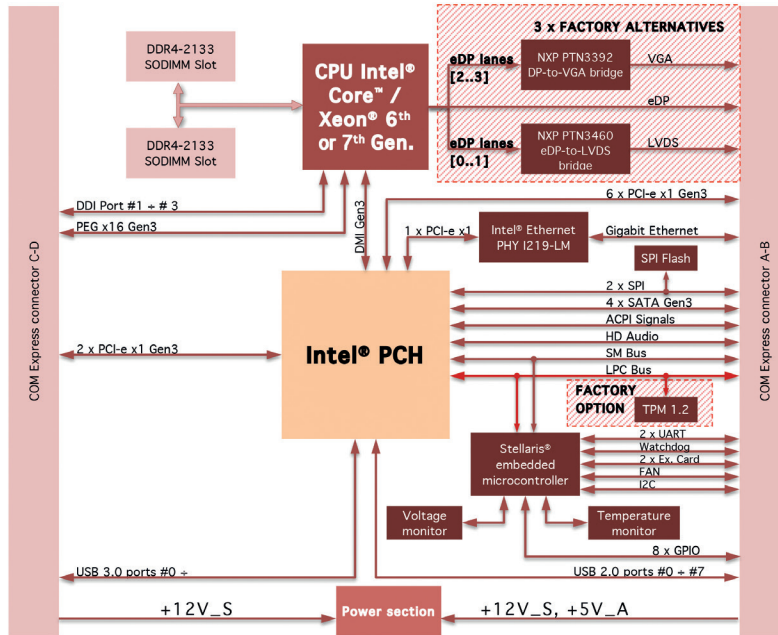
<b>Graphics</b>	Intel® HD Graphics 530 (6th Generation Core™ processors), P530 (6th Generation Xeon® processors) Intel® HD Graphics 630 (7th Generation Core™ processors), P630 (7th Generation Xeon® processors) Up to 3 independent displays supported DirectX® 12.1, OpenGL 4.4, and OpenCL 2.0 support HW accelerated video decode MPEG2, VC1 / WMV9, AVC / H.264, VP8, JPEG / MJPEG, HEVC / H.265, VP9 HW accelerated video encode MPEG2, AVC / H.264, VP8, JPEG / MJPEG, HEVC / H.265, VP9
<b>Video Interfaces</b>	Up to 3 x Digital Display Interfaces (DDIs), supporting DP 1.2, DVI and HDMI 1.4 eDP or Single / Dual-Channel 18- / 24- bit LVDS interface or LVDS + VGA interface PCI-express Graphics (PEG) Gen3 x16
<b>Video Resolution</b>	eDP, DP: up to 4096x2304 @60Hz, 24bpp HDMI: up to 4096x2160 @60Hz, 24bpp LVDS, VGA: up to 1920 x 1200 @60Hz
<b>Mass Storage</b>	4 x SATA Gen3 Channels
<b>Networking</b>	Gigabit Ethernet interface Intel® I219-LM GbE Controller
<b>USB</b>	4 x USB 3.0 Host ports 8 x USB 2.0 Host ports
<b>PCI-e</b>	8 x PCI-e x1 Gen3 lanes
<b>Audio</b>	HD Audio Interface
<b>Serial Ports</b>	2 x UARTs
<b>Other Interfaces</b>	2 x SPI, I2C, SM Bus, LPC Bus, 2 x Express Card, FAN management Optional TPM 1.2 LID# / SLEEP# / PWRBTN#, Watchdog 4x GPI, 4 x GPO
<b>Power Supply</b>	+12V <sub>DC</sub> ± 10% and +5V <sub>SB</sub> (optional)
<b>Operating System</b>	Microsoft® Windows 7 (only for Skylake) Microsoft® Windows 10 Linux
<b>Operating Temperature*</b>	0°C ÷ +60°C (Commercial version) -40°C / +70°C (Extended Temperature Range)
<b>Dimensions</b>	125 x 95 mm (Com Express™ Basic Form factor, Type 6 pinout)

\*Measured at any point of SECO standard heatspreader for this product, during any and all times (including start-up). Actual temperature will widely depend on application, enclosure and/or environment. Upon customer to consider application-specific cooling solutions for the final system to keep the heatspreader temperature in the range indicated.

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## BLOCK DIAGRAM



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